

## ABSTRACT

A solvent-free filling material comprising a filler,  
a thermosetting resin, a curing agent, and a curing catalyst,  
5 wherein the thermosetting resin is an epoxy resin, and the  
curing agent is a dicyandiamide curing agent; a multilayer  
printed wiring board comprising a substrate, a through-hole,  
the filling material filling the through-hole, and a conductor  
layer formed on an exposed surface of the filling material  
10 in the through-hole; and a process for producing the multilayer  
printed wiring board.